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Revision A is being issued to retract devices (with strikethrough) to correct the product affected section in the PCN email.

PCN Number:	20260710000.1A	PCN Issued	September 10, 2026
Datasheet for LM613x and LM614x		Estimated 1st ship date:	October 15, 2026

Change type(s)
Data Sheet/Electrical Specification

PCN Details

Description of Change:	
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.	
 LM6132, LM6134 SNOS751F – APRIL 2000 – REVISED JUNE 2026	
Changes from Revision E (September 2014) to Revision F (June 2026)	Page
• Deleted "Swing 0.01V to 4.99V" in <i>Features</i>	1
• Deleted Supply Current vs. Supply Voltage plot.....	1
• Deleted Offset Voltage vs. Supply Voltage plot.....	1
• Added Functional Block Diagram.....	1
• Updated table note 3 in <i>Absolute Maximum Ratings</i>	4
• Changed from (V-) – 0.3V to (V-) – 0.5V.....	4
• Changed from (V+) + 0.3V to (V+) + 0.5V.....	4
• Updated table note 4 in <i>Absolute Maximum Ratings</i>	4
• Updated table note 2 in <i>Absolute Maximum Ratings</i>	4
• Changed from ±25mA to Continuous.....	4
• Changed rating from Current at Output Pin to Output short circuit.....	4
• Added Operating ambient temperature rating.....	4
• Added CDM ESD rating.....	4
• Updated table note in <i>ESD Ratings</i>	4
• Added table note in <i>ESD Ratings</i>	4
• Deleted table note 1 in <i>Recommended Operating Conditions</i>	4
• Changed minimum supply voltage from 1.8V to 2.7V.....	4
• Changed Junction-to-case thermal resistance for LM6132D from 193°C/W to 127.1°C/W.....	5
• Changed Junction-to-case thermal resistance for LM6132P from 115°C/W to 84.45°C/W.....	5
• Added Junction-to-case (top) thermal resistance for packages.....	5
• Added Junction-to-board thermal resistance for packages.....	5
• Added Junction-to-top characterization parameter for packages.....	5

• Added Junction-to-board characterization parameter for packages.....	5
• Changed Junction-to-case thermal resistance for LM6134D from 126°C/W to 82.48°C/W.....	5
• Updated all <i>Electrical Characteristics</i> tables to latest format.....	6
• Updated Output Swing format to refer to rails.....	6
• Changed typical voltage output swing for 100kΩ load from 4.992V to 30mV from positive rail	6
• Changed maximum voltage output swing for 100kΩ load from 4.98V to 40mV from positive rail.....	6
• Changed typical voltage output swing for 100kΩ load from 0.007V to 30mV from negative rail.....	6
• Changed maximum voltage output swing for 100kΩ load from 0.017V to 35mV from negative rail.....	6
• Changed maximum voltage output swing for 100kΩ load over temperature from 0.019V to 50mV from negative rail.....	6
• Deleted table notes for all <i>Electric Characteristic</i> tables.....	6
• Updated Output Swing format to refer to rails.....	8
• Updated Output Swing format to refer to rails.....	9
• Added CMRR and PSRR vs Frequency plot for new die.....	10
• Added Gain and Phase vs Frequency plot for new die.....	10
• Added a new sub-section <i>Old Versus New Die Comparison</i>	15
• Deleted sub-section <i>Enhanced Slew Rate</i>	16

Changes from Revision D (March 2013) to Revision E (May 2026)
Page

• Deleted "Swing 0.005V to 4.995V" in <i>Features</i>	1
• Deleted "Small Signal, 5V/μs" in <i>Features</i>	1
• Deleted "Large Signal, 30V/μs" in <i>Features</i>	1
• Changed Slew Rate to Slew Rate: 30V/μs in <i>Features</i>	1
• Changed supply range from 1.8V to 2.7V in <i>Features</i>	1
• Changed from "Operating on supplies of 1.8V" to "Operating on supplies of 2.7V"	1
• Updated table note 1 of <i>Absolute Maximum Ratings</i>	5
• Changed absolute maximum rating for supply voltage from 35V to 33V	5
• Deleted absolute maximum rating for current at power supply pin	5
• Updated table note 3 of <i>Absolute Maximum Ratings</i>	5
• Changed absolute maximum rating for input (common-mode) voltage from (V _±) ± 0.3V to (V _±) ± 0.5V	5
• Updated table note 4 of <i>Absolute Maximum Ratings</i>	5
• Changed absolute maximum rating for differential input voltage from 15V to ±15V	5
• Updated table note 2 of <i>Absolute Maximum Ratings</i>	5
• Changed absolute maximum rating for output current from ±25mA to Continuous	5
• Added absolute maximum rating for operating ambient temperature	5
• Deleted absolute maximum rating for lead temperature	5
• Added <i>ESD Ratings</i> table	5
• Changed HBM ESD rating from 2500V to ±4000V	5
• Changed minimum operating voltage from 1.8V to 2.7V	5
• Deleted table note 1 on Operating Ratings	5
• Added <i>Thermal Information</i> table for LM6142	6
• Changed junction-to-ambient thermal resistance for LM6142D from 193°C/W to 127.1°C/W	6
• Changed junction-to-ambient thermal resistance for LM6142P from 115°C/W to 84.45°C/W	6
• Added junction-to-case thermal resistance for LM6142	6
• Added junction-to-board thermal resistance for LM6142	6
• Added junction-to-top characterization parameter for LM6142	6
• Added junction-to-board characterization parameter for LM6142	6
• Added <i>Thermal Information</i> table for LM6144	6
• Changed junction-to-ambient thermal resistance for LM6144D from 126°C/W to 82.48°C/W	6
• Added junction-to-case (top) thermal resistance for LM6144	6
• Added junction-to-board thermal resistance for LM6144	6
• Added junction-to-top characterization parameter for LM6144	6
• Added junction-to-board characterization parameter for LM6144	6
• Updated all <i>Electrical Characteristics</i> tables to latest format	7
• Updated Output Swing format to refer to rails	7
• Changed typical voltage output swing for 100kΩ load from 4.995V to 30mV from positive rail	7
• Changed maximum voltage output swing for 100kΩ load from 4.98V to 40mV from positive rail	7
• Changed typical voltage output swing for 100kΩ load from 0.005V to 45mV from negative rail	7
• Changed maximum voltage output swing for 100kΩ load from 0.01V to 50mV from negative rail	7
• Changed maximum voltage output swing for 100kΩ load over temp range from 0.013V to 60mV from negative rail	7
• Changed typical voltage output swing for 10kΩ load from 4.97V to 40mV from positive rail	7
• Changed typical voltage output swing for 10kΩ load from 0.02V to 50mV from negative rail	7
• Deleted table notes for <i>Electrical Characteristics</i> tables	7
• Updated Output Swing format to refer to rails	9
• Changed maximum voltage output swing for 100kΩ load from 2.66V to 75mV from positive rail	9
• Updated Output Swing format to refer to rails	10

The datasheet number will be changing.

Device Family	Change From:	Change To:
LM613x	SNOS751E	SNOS751F
LM614x	SNOS726D	SNOS726E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LM6132>

<http://www.ti.com/product/LM6142>

Reason for Change:	To accurately reflect device characteristics.
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	There are changes in the electrical tables.
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Changes to product identification resulting from this PCN:	None
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Products Affected:

LM6134BIN/NOPB	LM6142 MWC	LM6142-MWC.A	LM6144BIN/NOPB
LM6132AIM	LM6132AIM/NOPB	LM6132AIMX	LM6132BIM
LM6132BIM/NOPB	LM6132BIMX	LM6132BIMX/SL110236	LM6132BIN
LM6134AIM	LM6134AIM/NOPB	LM6134AIMX	LM6134BIM
LM6134BIM/NOPB	LM6134BIMX	LM6134BIMX/E7001806	LM6134BIMX/SL110237
LM6134BIN			

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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